

# Solar Wafer Cleaning System

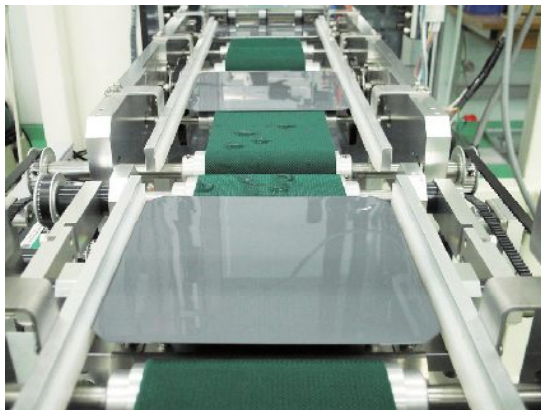
## Pre-cleaning system

### Features:

- Optimized cleaning efficiency for slurry removal and glue stripping of saw-sliced ingot
- High throughput design of batch type transportation

### Specifications:

- Applicable wafer size: □104mm, □125mm, □156mm
- Applicable wafer thickness: Down to 160 μm
- Throughput: Max. 6,000 wafers/h  
(1 ingot = 1,500 wafers)



**PATENT.PENDING.**

## Wafer separator

### Features:

- Stacked-wafer separation system after pre-cleaning process
- Optional breakage discharge function available
- Optional automatic transportation system to wafer-cassette or loading position of the final cleaning system available

### Specifications:

- Applicable wafer size: □104mm, □125mm, □156mm
- Applicable wafer thickness: Down to 160 μm
- Throughput: Max. 2,400 wafers/h

## Final cleaning system

### Features:

- 2 kinds of line-up, Batch processing type and Single processing type
- Optimized cleaning by surfactant and ultrasonic

### Specifications:

- Applicable wafer size: □104mm, □125mm, □156mm
- Applicable wafer thickness: down to 160 μm
- Throughput: Max. 2,400 wafers/h (Batch type)  
(1 batch= 200 wafers)
- Throughput: Max. 3,600 wafers/h (Single type)  
(6-Lane case)

